



27C256

## 256K (32K x 8) CMOS EPROM

## FEATURES

- High speed performance
  - 90 ns access time available
- CMOS Technology for low power consumption
  - 20 mA Active current
  - 100  $\mu$ A Standby current
- Factory programming available
- Auto-insertion-compatible plastic packages
- Auto ID aids automated programming
- Separate chip enable and output enable controls
- High speed “express” programming algorithm
- Organized 32K x 8: JEDEC standard pinouts
  - 28-pin Dual-in-line package
  - 32-pin PLCC Package
  - 28-pin SOIC package
  - 28-pin Thin Small Outline Package (TSOP)
  - 28-pin Very Small Outline Package (VSOP)
  - Tape and reel
- Data Retention > 200 years
- Available for the following temperature ranges:
  - Commercial: 0°C to +70°C
  - Industrial: -40°C to +85°C
  - Automotive: -40°C to +125°C

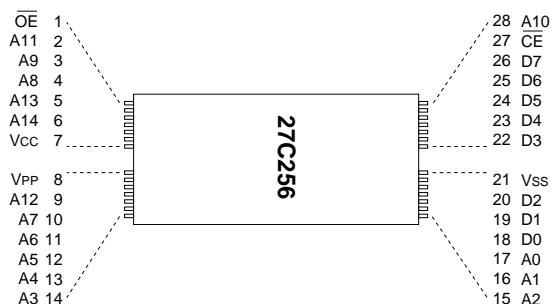
## DESCRIPTION

The Microchip Technology Inc. 27C256 is a CMOS 256K bit electrically Programmable Read Only Memory (EPROM). The device is organized as 32K words by 8 bits (32K bytes). Accessing individual bytes from an address transition or from power-up (chip enable pin going low) is accomplished in less than 90 ns. This very high speed device allows the most sophisticated micro-processors to run at full speed without the need for WAIT states. CMOS design and processing enables this part to be used in systems where reduced power consumption and reliability are requirements.

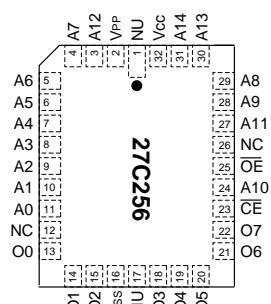
A complete family of packages is offered to provide the most flexibility in applications. For surface mount applications, PLCC, SOIC, VSOP or TSOP packaging is available. Tape and reel packaging is also available for PLCC or SOIC packages.

## PACKAGE TYPES

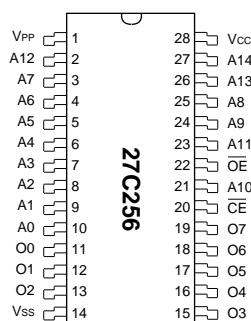
TSOP



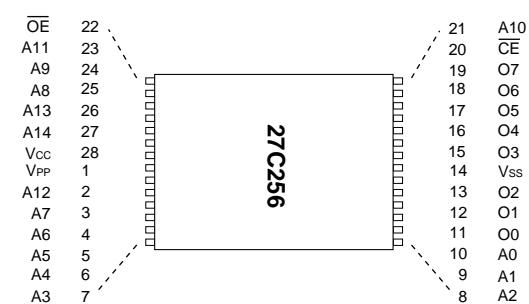
PLCC



DIP/SOIC



VSOP



## 1.0 ELECTRICAL CHARACTERISTICS

### 1.1 Maximum Ratings\*

Vcc and input voltages w.r.t. Vss ..... -0.6V to +7.25V  
 VPP voltage w.r.t. Vss during programming ..... -0.6V to +14.0V  
 Voltage on A9 w.r.t. Vss ..... -0.6V to +13.5V  
 Output voltage w.r.t. Vss ..... -0.6V to Vcc +1.0V  
 Storage temperature ..... -65°C to +150°C  
 Ambient temp. with power applied ..... -65°C to +125°C

\*Notice: Stresses above those listed under "Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

TABLE 1-1: PIN FUNCTION TABLE

Name	Function
A0-A14	Address Inputs
$\overline{CE}$	Chip Enable
$\overline{OE}$	Output Enable
VPP	Programming Voltage
O0 - O7	Data Output
Vcc	+5V Power Supply
Vss	Ground
NC	No Connection; No Internal Connection
NU	Not Used; No External Connection Is Allowed

TABLE 1-2: READ OPERATION DC CHARACTERISTICS

VCC = +5V ( $\pm 10\%$ )							
Parameter	Part*	Status	Symbol	Min.	Max.	Units	Conditions
Input Voltages	all	Logic "1" Logic "0"	VIH VIL	2.0 -0.5	VCC+1 0.8	V V	
Input Leakage	all	—	ILI	-10	10	$\mu$ A	$V_{IN} = 0$ to Vcc
Output Voltages	all	Logic "1" Logic "0"	VOH VOL	2.4	0.45	V V	$I_{OH} = -400 \mu A$ $I_{OL} = 2.1 \text{ mA}$
Output Leakage	all	—	LO	-10	10	$\mu$ A	$V_{OUT} = 0V$ to Vcc
Input Capacitance	all	—	C <sub>IN</sub>	—	6	pF	$V_{IN} = 0V$ ; Tamb = 25°C; f = 1 MHz
Output Capacitance	all	—	C <sub>OUT</sub>	—	12	pF	$V_{OUT} = 0V$ ; Tamb = 25°C; f = 1 MHz
Power Supply Current, Active	C I,E	TTL input TTL input	ICC1 ICC2	— —	20 25	mA mA	Vcc = 5.5V; VPP = Vcc f = 1 MHz; $\overline{OE} = \overline{CE} = V_{IL}$ ; $I_{OUT} = 0 \text{ mA}$ ; $V_{IL} = -0.1$ to 0.8V; $VIH = 2.0$ to Vcc; Note 1
Power Supply Current, Standby	C I, E all	TTL input TTL input CMOS input	ICC(s)	—	2 3 100	mA mA $\mu$ A	$\overline{CE} = V_{CC} \pm 0.2V$
I <sub>PP</sub> Read Current V <sub>PP</sub> Read Voltage	all all	Read Mode Read Mode	I <sub>PP</sub> V <sub>PP</sub>	Vcc-0.7	100 Vcc	$\mu$ A V	V <sub>PP</sub> = 5.5V

\* Parts: C=Commercial Temperature Range; I, E=Industrial and Extended Temperature Ranges

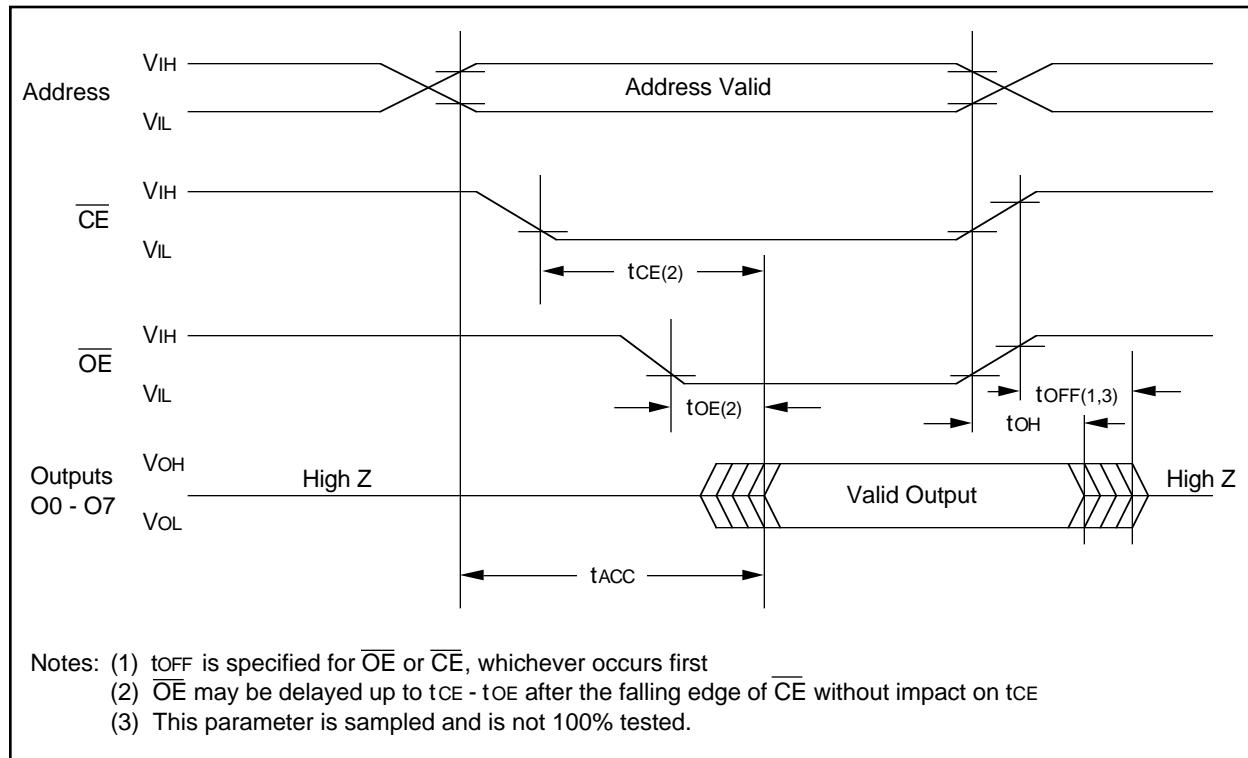
Note 1: Typical active current increases .75 mA per MHz up to operating frequency for all temperature ranges.

TABLE 1-3: READ OPERATION AC CHARACTERISTICS

AC Testing Waveform: $V_{IH} = 2.4V$ and $V_{IL} = 0.45V$ ; $V_{OH} = 2.0V$ $V_{OL} = 0.8V$ Output Load: 1 TTL Load + 100 pF Input Rise and Fall Times: 10 ns Ambient Temperature: Commercial: $T_{amb} = 0^{\circ}C$ to $+70^{\circ}C$ Industrial: $T_{amb} = -40^{\circ}C$ to $+85^{\circ}C$ Automotive: $T_{amb} = -40^{\circ}C$ to $+125^{\circ}C$													
Parameter	Sym	27C256-90*		27C256-10*		27C256-12		27C256-15		27C256-20		Units	Conditions
		Min	Max	Min	Max	Min	Max	Min	Max	Min	Max		
Address to Output Delay	tACC	—	90	—	100	—	120	—	150	—	200	ns	$\overline{CE} = \overline{OE} = V_{IL}$
$\overline{CE}$ to Output Delay	tCE	—	90	—	100	—	120	—	150	—	200	ns	$\overline{OE} = V_{IL}$
$\overline{OE}$ to Output Delay	toE	—	40	—	45	—	55	—	65	—	75	ns	$\overline{CE} = V_{IL}$
$\overline{CE}$ or $\overline{OE}$ to O/P High Impedance	toFF	0	30	0	30	0	35	0	50	0	55	ns	
Output Hold from Address $\overline{CE}$ or $\overline{OE}$ , whichever goes first	toH	0	—	0	—	0	—	0	—	0	—	ns	

\* -10, -90 AC Testing Waveform:  $V_{IH} = 2.4V$  and  $V_{IL} = .45V$ ;  $V_{OH} = 1.5V$  and  $V_{OL} = 1.5V$   
 Output Load: 1 TTL Load + 30pF

FIGURE 1-1: READ WAVEFORMS



**TABLE 1-4: PROGRAMMING DC CHARACTERISTICS**

Ambient Temperature: Tamb = 25°C ± 5°C VCC = 6.5V ± 0.25V, VPP = VH = 13.0V ± 0.25V						
Parameter	Status	Symbol	Min	Max.	Units	Conditions
Input Voltages	Logic"1" Logic"0"	VIH VIL	2.0 -0.1	VCC+1 0.8	V V	
Input Leakage	—	ILI	-10	10	µA	VIN = 0V to VCC
Output Voltages	Logic"1" Logic"0"	VOH VOL	2.4	0.45	V V	IOH = -400 µA IOL = 2.1 mA
VCC Current, program & verify	—	ICC2	—	20	mA	Note 1
VPP Current, program	—	IPP2	—	25	mA	Note 1
A9 Product Identification	—	VH	11.5	12.5	V	

Note 1: VCC must be applied simultaneously or before VPP and removed simultaneously or after VPP

**TABLE 1-5: PROGRAMMING AC CHARACTERISTICS**

for Program, Program Verify and Program Inhibit Modes	AC Testing Waveform: VIH=2.4V and VIL=0.45V; VOH=2.0V; VOL=0.8V Output Load: 1 TTL Load + 100pF Ambient Temperature: Tamb=25°C ± 5°C VCC= 6.5V ± 0.25V, VPP = VH = 13.0V ± 0.25V				
Parameter	Symbol				
Address Set-Up Time	tAS				
Data Set-Up Time	tDS				
Data Hold Time	tDH				
Address Hold Time	tAH				
Float Delay (2)	tDF				
VCC Set-Up Time	tVCS				
Program Pulse Width (1)	tPW				
CE Set-Up Time	tCES				
OE Set-Up Time	tOES				
VPP Set-Up Time	tVPS				
Data Valid from OE	toE				
Parameter	Symbol	Min.	Max.	Units	Remarks
Address Set-Up Time	tAS	2	—	µs	
Data Set-Up Time	tDS	2	—	µs	
Data Hold Time	tDH	2	—	µs	
Address Hold Time	tAH	0	—	µs	
Float Delay (2)	tDF	0	130	ns	
VCC Set-Up Time	tVCS	2	—	µs	
Program Pulse Width (1)	tPW	95	105	µs	100 µs typical
CE Set-Up Time	tCES	2	—	µs	
OE Set-Up Time	tOES	2	—	µs	
VPP Set-Up Time	tVPS	2	—	µs	
Data Valid from OE	toE	—	100	ns	

Note 1: For express algorithm, initial programming width tolerance is 100 µs ±5%.

2: This parameter is only sampled and not 100% tested. Output float is defined as the point where data is no longer driven (see timing diagram).

FIGURE 1-2: PROGRAMMING WAVEFORMS

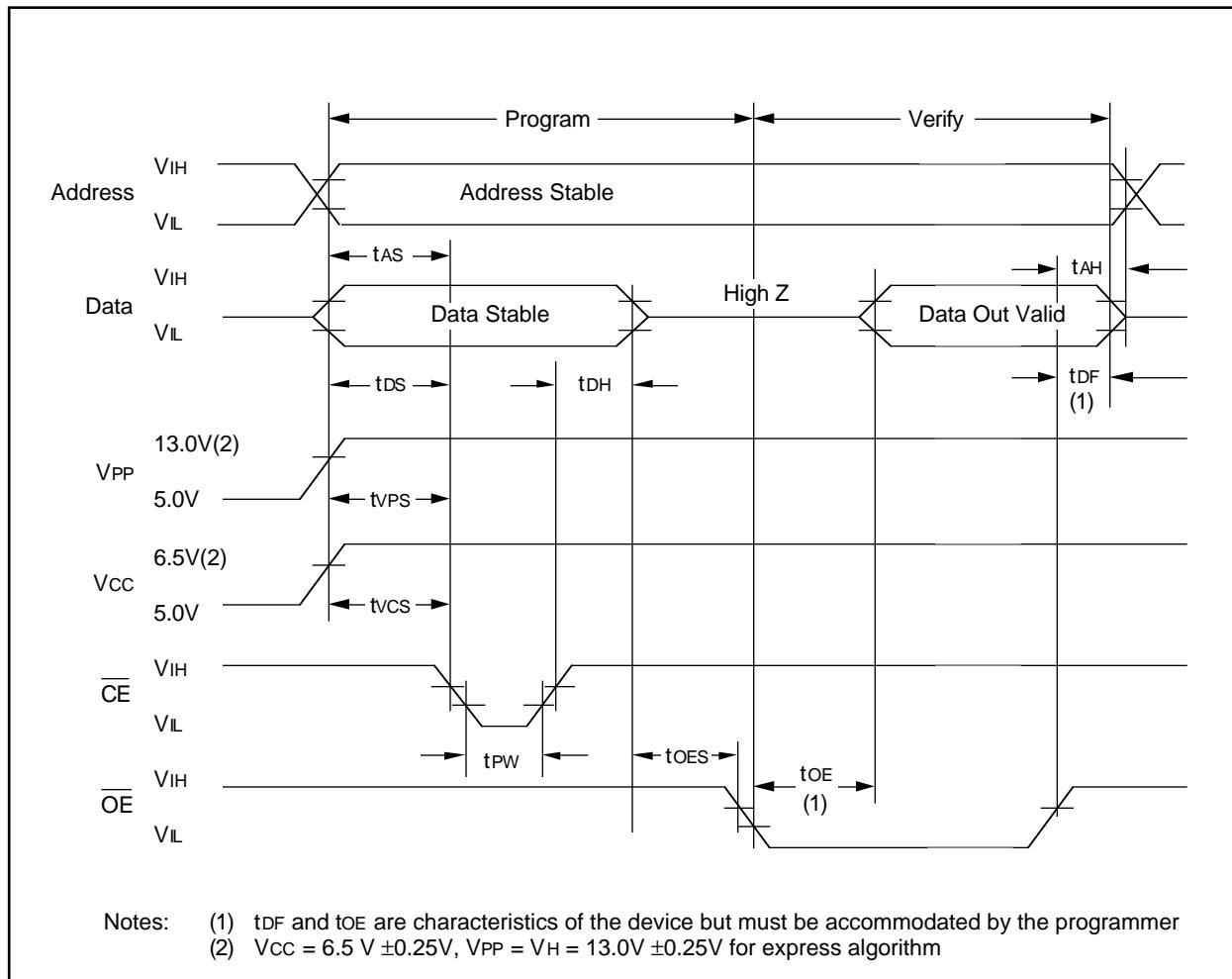


TABLE 1-6: MODES

Operation Mode	CE	OE	VPP	A9	O0 - O7
Read	VIL	VIL	VCC	X	DOUT
Program	VIL	VIH	VH	X	DIN
Program Verify	VIH	VIL	VH	X	DOUT
Program Inhibit	VIH	VIH	VH	X	High Z
Standby	VIH	X	VCC	X	High Z
Output Disable	VIL	VIH	VCC	X	High Z
Identity	VIL	VIL	VCC	VH	Identity Code

X = Don't Care

## 1.2 Read Mode

(See Timing Diagrams and AC Characteristics)

Read Mode is accessed when:

- the  $\overline{CE}$  pin is low to power up (enable) the chip
- the  $\overline{OE}$  pin is low to gate the data to the output pins

For Read operations, if the addresses are stable, the address access time (tACC) is equal to the delay from  $\overline{CE}$  to output (tCE). Data is transferred to the output after a delay from the falling edge of  $\overline{OE}$  (toE).

## 1.3 Standby Mode

The standby mode is defined when the  $\overline{CE}$  pin is high (VIH) and a program mode is not defined.

When these conditions are met, the supply current will drop from 20 mA to 100  $\mu$ A.

## 1.4 Output Enable

This feature eliminates bus contention in multiple bus microprocessor systems and the outputs go to a high impedance when the following condition is true:

- The  $\overline{OE}$  pin is high and the program mode is not defined.

## 1.5 Erase Mode (U.V. Windowed Versions)

Windowed products offer the ability to erase the memory array. The memory matrix is erased to the all 1's state when exposed to ultraviolet light. To ensure complete erasure, a dose of 15 watt-second/cm<sup>2</sup> is required. This means that the device window must be placed within one inch and directly underneath an ultraviolet lamp with a wavelength of 2537 Angstroms, intensity of 12,000  $\mu$ W/cm<sup>2</sup> for approximately 20 minutes.

## 1.6 Programming Mode

The Express Algorithm has been developed to improve on the programming throughput times in a production environment. Up to ten 100-microsecond pulses are applied until the byte is verified. No overprogramming is required. A flowchart of the express algorithm is shown in Figure 1-3.

Programming takes place when:

- a) Vcc is brought to the proper voltage,
- b) VPP is brought to the proper VH level,
- c) the  $\overline{OE}$  pin is high, and
- d) the  $\overline{CE}$  pin is low.

Since the erased state is "1" in the array, programming of "0" is required. The address to be programmed is set via pins A0-A14 and the data to be programmed is presented to pins O0-O7. When data and address are stable, a low going pulse on the  $\overline{CE}$  line programs that location.

## 1.7 Verify

After the array has been programmed it must be verified to ensure all the bits have been correctly programmed. This mode is entered when all the following conditions are met:

- a) Vcc is at the proper level,
- b) VPP is at the proper VH level,
- c) the  $\overline{CE}$  line is high, and
- d) the  $\overline{OE}$  line is low.

## 1.8 Inhibit

When programming multiple devices in parallel with different data, only  $\overline{CE}$  need be under separate control to each device. By pulsing the  $\overline{CE}$  line low on a particular device, that device will be programmed; all other devices with  $\overline{CE}$  held high will not be programmed with the data, although address and data will be available on their input pins.

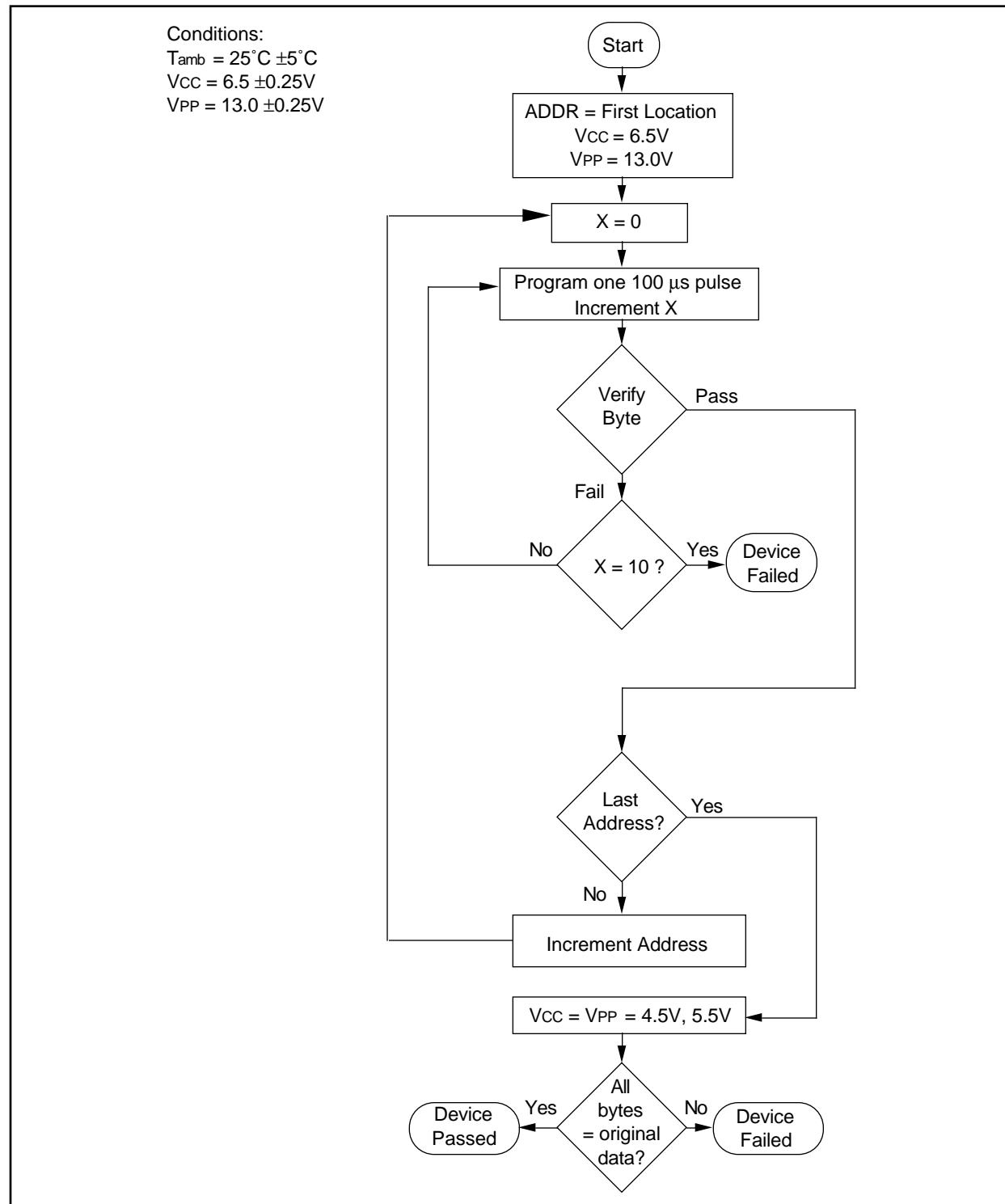
## 1.9 Identity Mode

In this mode specific data is output which identifies the manufacturer as Microchip Technology Inc. and device type. This mode is entered when Pin A9 is taken to VH (11.5V to 12.5V). The  $\overline{CE}$  and  $\overline{OE}$  lines must be at VIL. A0 is used to access any of the two non-erasable bytes whose data appears on O0 through O7.

Pin →	Input	Output								Hex
		0 7	0 6	0 5	0 4	0 3	0 2	0 1	0 0	
Identity ↓	A0	0 7	0 6	0 5	0 4	0 3	0 2	0 1	0 0	29 8C
Manufacturer	VIL	0	0	1	0	1	0	0	1	
Device Type*	VIH	1	0	0	0	1	1	0	0	8C

\* Code subject to change

FIGURE 1-3: PROGRAMMING EXPRESS ALGORITHM



# 27C256

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## NOTES:

## NOTES:

# 27C256

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## NOTES:

# 27C256

## **27C256 Product Identification System**

To order or to obtain information (e.g., on pricing or delivery), please use listed part numbers, and refer to factory or listed sales offices.

<b>27C256</b>	<b>-</b>	<b>90</b>	<b>I</b>	<b>/TS</b>			
					<b>Package:</b>	L	Plastic Leaded Chip Carrier
						P	Plastic DIP (Mil 600)
						SO	Plastic SOIC (Mil 300)
						TS	Thin Small Outline Package (TSOP) 8x20mm
						VS	Very Small Outline Package (VSOP) 8x13.4mm
			<b>Temperature</b>	<b>Range:</b>	Blank	=	0°C to +70°C
					I	=	-40°C to +85°C
					E	=	-40°C to +125°C
			<b>Access</b>	<b>Time:</b>	90	=	90 ns
					10	=	100 ns
					12	=	120 ns
					15	=	150 ns
					20	=	200 ns
			<b>Device</b>		27C256		256K (32K x 8) CMOS EPROM

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